



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD042P03L3 G	Issued	12. May 2021
MA#	MA001702446		
Package	PG-TO252-3-313	Weight*	320.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.261	1.33	1.33	13305	13305
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		460	
	non noble metal	copper	7440-50-8	147.096	45.93	45.99	459304	459902
wire	non noble metal	aluminium	7429-90-5	3.304	1.03	1.03	10318	10318
encapsulation	inorganic material	zinc oxide	1314-13-2	1.377	0.43		4299	
	miscellaneous	miscellaneous	-	6.884	2.15		21495	
	plastics	epoxy resin	-	20.652	6.45		64484	
	inorganic material	silicon dioxide	60676-86-0	108.765	33.96	42.99	339616	429894
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11678	11678
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4436	4447
solder	non noble metal	tin	7440-31-5	0.067	0.02		210	
	noble metal	silver	7440-22-4	0.084	0.03		262	
	non noble metal	lead	7439-92-1	3.211	1.00	1.05	10025	10497
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59881	59959
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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